## BOARD CHARACTERISTICS

| | | | |
|---|---|---|---|
| Copper Layer Count: | 4 | Board Thickness: | 1.6400 mm |
| Board overall dimensions: | 75.0000 mm x 50.0000 mm | | |
| Min track/spacing: | 0.1200 mm / 0.1200 mm | Min hole diameter: | 0.2000 mm |
| Copper Finish: | ENIG | Impedance Control: | Yes |
| Castellated pads: | No | Plated Board Edge: | No |
| Edge card connectors: | No | | |

90 Ohm ±10% differential impedance required on
0.18 mm traces/ 0.12 mm spacing on layers 1 and 4 (Top and Bottom)

| Layer Name | Type | Material | Thickness (mm) | Color | Epsilon R | Loss Tangent |
|---|---|---|---|---|---|---|
| F.Silkscreen | Top Silk Screen | Not specified | 0 mm | White | 1 | 0 |
| F.Paste | Top Solder Paste | | 0 mm | | 1 | 0 |
| F.Mask | Top Solder Mask | Not specified | 0.01 mm | Black | 3.3 | 0 |
| F.Cu | copper | | 0.035 mm | | 1 | 0 |
| Dielectric | prepreg | FR4 | 0.14 mm | Not specified | 4 | 0.02 |
| In1.Cu | copper | | 0.035 mm | | 1 | 0 |
| Dielectric | core | FR4 | 1.2 mm | Not specified | 4.6 | 0.02 |
| In2.Cu | copper | | 0.035 mm | | 1 | 0 |
| Dielectric | prepreg | FR4 | 0.14 mm | Not specified | 4 | 0.02 |
| B.Cu | copper | | 0.035 mm | | 1 | 0 |
| B.Mask | Bottom Solder Mask | Not specified | 0.01 mm | Black | 3.3 | 0 |

75.0

10.0

10.0

50.0

40.0 mm

5.0 mm

R 3.0

R 1.6

30.0

PCB Edge

Sheet:
File: usb3-gmm7550.kicad_pcb
### Title: GMM-7550 USB3 Adapter

| Size: A4 | Date: 2025-10-16 | Rev: 1.0 |
|---|---|---|
| KiCad E.D.A. 9.0.3 | | Id: 9/11 |